AMENDMENTS TO THE CLAIMS

Please amend claims 1-9. Please withdraw claims 3, 4 and 16-21. A listing of all claims and their current status in accordance with 37 C.F.R. § 1.121(c) is provided below.

1.   (Currently Amended)   A holder~~shipping package~~ having a plurality of semiconductor die stacks thereon, the holder~~shipping package~~ being adapted to temporarily hold the plurality of semiconductor die stacks.

2.   (Currently Amended)   The holder~~shipping package~~, as set forth in claim 1, comprising a tape reel having the plurality of semiconductor die stacks thereon.

3.   (Withdrawn)   The holder~~shipping package~~, as set forth in claim 1, comprising a gel pack having the plurality of semiconductor die stacks thereon.

4.   (Withdrawn)   The holder~~shipping package~~, as set forth in claim 1, comprising a tray having the plurality of semiconductor die stacks thereon.

5.   (Currently Amended)   The holder~~shipping package~~, as set forth in claim 1, wherein each of the die stacks comprises at least two semiconductor die, each of the semiconductor die being coupled together by an adhesive.

6.   (Currently Amended)   The holder~~shipping package~~, as set forth in claim 5, wherein one of the at least two semiconductor die is thicker than a second of the at least two semiconductor die.

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7. (Currently Amended) The holder~~shipping package~~, as set forth in claim 5, wherein the topside surface area of one of the at least two semiconductor die is less than the topside surface area of a second of the at least two semiconductor die.

8. (Currently Amended) The holder~~shipping package~~, as set forth in claim 5, wherein the stack of at least two semiconductor die is configured such that the stack comprises a shingle stack.

9. (Currently Amended) The holder~~shipping package~~, as set forth in claim 5, wherein at least one of the at least two semiconductor die comprises a memory die.

10. (Original) A tape reel having a plurality of semiconductor die stacks thereon, the tape reel being adapted to temporarily hold the plurality of semiconductor die stacks.

11. (Original) The tape reel, as set forth in claim 10, wherein each of the die stacks comprises at least two semiconductor die, each of the semiconductor die being coupled together by an adhesive.

12. (Original) The tape reel, as set forth in claim 11, wherein one of the at least two semiconductor die is thicker than a second of the at least two semiconductor die.

13. (Original) The tape reel, as set forth in claim 11, wherein the topside surface area of one of the at least two semiconductor die is less than the topside surface area of a second of the at least two semiconductor die.

14. (Original) The tape reel, as set forth in claim 11, wherein the stack of at least two semiconductor die is configured such that the stack comprises a shingle stack.

15. (Original) The tape reel, as set forth in claim 11, wherein at least one of the at least two semiconductor die comprises a memory die.

16. (Withdrawn) A gel pack having a plurality of semiconductor die stacks thereon, the gel pack being adapted to temporarily hold the plurality of semiconductor die stacks.

17. (Withdrawn) The gel pack, as set forth in claim 16, wherein each of the die stacks comprises at least two semiconductor die, each of the semiconductor die being coupled together by an adhesive.

18. (Withdrawn) The gel pack, as set forth in claim 16, wherein one of the at least two semiconductor die is thicker than a second of the at least two semiconductor die.

19. (Withdrawn) The gel pack, as set forth in claim 16, wherein the topside surface area of one of the at least two semiconductor die is less than the topside surface area of a second of the at least two semiconductor die.

20.   (Withdrawn) The gel pack, as set forth in claim 16, wherein the stack of at least two semiconductor die is configured such that the stack comprises a shingle stack.

21.   (Withdrawn) The gel pack, as set forth in claim 16, wherein at least one of the at least two semiconductor die comprises a memory die.